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RI

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Patent And Trademark Office

102703613

To the Honorable Commissioner of Patents and Trademark.

This document is the original document or copy thereof.

1. Name of conveying party(ies):

	Date
Bradley O. Stimson	12-11-98
Mitsuhiro Kaburaki	1-21-99
John C. Forster	12-12-98
Eric Delaurentis	12-11-98
Praburam Gopalraja	12-9-98
Patricia Rodriguez	12-11-98
Anantha Subramani	12-11-98

3-19-04

2. Name and address of receiving party(ies):

Name: Applied Materials, Inc.Internal Address: P.O. Box 450-A

Street Address: _____

City: Santa Clara State: CA Zip: 95052Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: SEE ABOVEAdditional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

10804254

If this document is being filed together with a new application, the execution date of the application is: _____ (Date of Filing)

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Patent CounselInternal Address: APPLIED MATERIALS, INC.Street Address: P.O. Box 450-ACity: Santa Clara State: CA Zip: 950526. Total number of applications and patents involved: 17. Total fee (37 C.F.R. 3.41) _____ \$ 40.00☐ Enclosed☒ Authorized to be charged to deposit account

8. Deposit account number:

20-0782

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Keith Taboada, Esq.

Name of Person Signing

Reg. No. 45,150

Signature

Date

Mar 19, 2004

Total number of pages including cover sheet, attachments and document:

260734

03/24/2004 NBETACHE 00000159 200782 10804254

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40.00 DA

PATENT
REEL: 015121 FRAME: 0943

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- | | |
|---|--|
| 1) Bradley O. Stimson
1257 Hanchett Avenue
San Jose, CA 95126 | 5) Praburam Gopalraja
1235 Wildwood Ave. Apt 277
Sunnyvale, CA 94089 |
| 2) Mitsuhiro Kaburaki
3-5-22-404 Hashigadai
Narita City, Chiba, Japan 286 | 6) Patricia Rodriguez
2200 Agnew, #316
Santa Clara, CA 95054 |
| 3) John C. Forster
41 Hallam
San Francisco, CA 94103 | 7) Anantha Subramani
3098 Linkfield Way
San Jose, CA 95135 |
| 4) Eric Delaurentis
19009 Two Bar Road
Boulder Creek, CA 95006 | |

(hereinafter referred to as Assignors), have invented a certain invention entitled:

APPARATUS FOR IMPROVED POWER COUPLING THROUGH A WORKPIECE IN A SEMICONDUCTOR WAFER PROCESSING SYSTEM

for which we have filed an application for a Patent of the United States on October 29, 1998,
Serial No. 09/182,023; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division,

substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) _____, 1998

Bradley O. Stimson

2)

Jan 21st, ~~1998~~ ¹⁹⁹⁹

Mitsuhiro Kaburaki
Mitsuhiro Kaburaki

3) _____, 1998

John C. Forster

4) _____, 1998

Eric Delaurentis

5) _____, 1998

Praburam Gopalraja

6) _____, 1998

Patricia Rodriguez

7)

1998

Anantha Subramani

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- | | |
|---|---|
| 1) Bradley O. Stimson
1257 Hanchett Avenue
San Jose, CA 95126 | 5) Praburam Gopalraja
1235 Wildwood Ave. Apt 277
Sunnyvale, CA 94089 |
| 2) Mitsuhiro Kaburaki
3-5-22-404 Hashigadai
Narita City, Chiba, Japan 286 | 6) Patricia Rodriguez
2200 Agnew, #316 1267 Fremont St
Santa Clara, CA 95054 95050 |
| 3) John C. Forster
41 Hallam
San Francisco, CA 94103 | 7) Anantha Subramani
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San Jose, CA 95135 |
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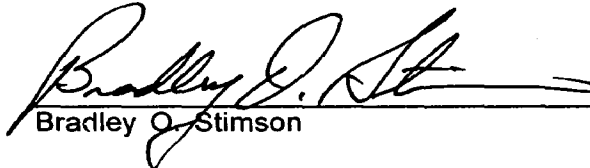
2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

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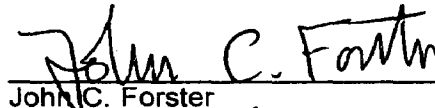
1) Dec. 11th, 1998


Bradley O. Stimson

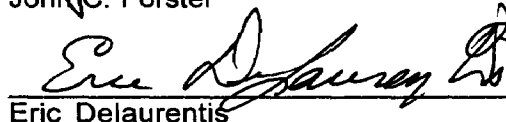
2) _____, 1998

Mitsuhiro Kaburaki

3) Dec 12th, 1998


John C. Forster

4) Dec 11/98, 1998


Eric Delaurentis

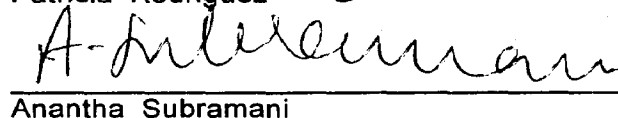
5) Dec 9th, 1998


Praburam Gopalraja

6) Dec 11th, 1998


Patricia Rodriguez

7) Dec 11th, 1998


Anantha Subramani